

Alexander D. Glew, Ph.D., P.E.

Expertise

• Materials Science	Engineering, Thin	•	Mechanical Engineering
Films & Equipmer	nt, Semiconductor		
Semiconductor Equ	ipment and	•	Licensed Professional Engineer (PE) in
processing: CVD, E	Etch, RIE, CMP,		California, Mechanical Engineering
SOD, EPI, MBE, R	TP, and others		, C C
Chemical vapor der	position (CVD):	•	CAD, drafting standards, and related.
plasma, ICP, therma	al. MOCVD. LPCVD		, 8
and others	, 1110012, 11012		
Thin film processin	g for solar LED and	•	Computation Fluid Dynamics (CFD)
ontics	g for solar, LLD, and	•	Fluid flow radiation analysis
 Diamond Like Carb 	on (DI C)	•	Finite Element Analysis (EEA) multi
Diamond Like Call	$\int O(I) (DLC),$	•	Philice Element Analysis (PEA), multi-
Fluorinated amorph	ious carbon (FLAC)		physics and event simulation
Dielectric Deposition	on: Low k dielectric	•	Product Design & Testing
films, SiO2 (glass),	fluorinated glass		
(FSG), BPSG, USG	Ĵ		
Excimer Laser Sour	rces	•	Project management and turnaround
• Laboratory analysis	SEM, TEM, FTIR,	•	Ultra High Purity Gas and Chemical
SIMS, AES, and oth	hers.		Delivery Systems
Materials processin	g	•	Piping, valve, and chemical systems
Metal deposition an	d sputtering (PVD)	•	Metrology: Flow, pressure, optical
1			properties, thin film properties
Plasma and Therma	1 Processes	•	Reverse Engineering
		-	
• Thin Film Characte	rization: stress, strain,	•	Safety analysis, interlocks, failure mode
thickness, optical a	nd dielectric		effects, standards and code analysis.
properties, structure	e. composition		

ASM Ex. 1004 IPR Petition - USP 7,808,396

Employment History

From: 1997 Glew Engineeri To: Present Mountain View, Position: President		Glew Engineering Consulting, Inc. Mountain View, California President
		Clients include companies from semiconductor equipment, plasma generation, vacuum systems, fluid delivery systems, flow and pressure component suppliers, laser manufacturers, consumer electronics, industrial electronics, vehicle, telecommunications, and others. Consulting work includes thin film characterization, process development, project turn- around/rescue, gas flow and vacuum metrology, design of experiments, corrosive gas applications, finite element analysis and related market analysis.
From:	Aug 1987	Applied Materials, Inc.
To:	Jan 1997	Santa Clara, California
	Titles	Engineering Manager, Core-Technologist
	Project Mgr.	• Sat on corporate engineering/technology (ET) council,
	Jan 1990 to Jan 1997	in gas delivery technology for all divisions including CVD EPI
	Juli 1997	PVD RTP etch thermal and others. Also qualified gas and
		vacuum component selections. Consulted with all divisions on
		gas and vacuum systems, liquid source delivery systems,
		components, and supplier selections.
		• Received patent for improved tungsten (W) CVD
		deposition.
		• Successfully proposed and executed a project that
		SEMATECH S100 funded. The goal was to develop industry
		methods to determine the effects of trace chemicals on
		resulted in two SEMATECH Technology Transfers listed below
	CVD	First, ppb levels of impurities were introduced into both a
	Supplier	Tungsten CVD deposition process and an aluminum etching
	Quality	process. The effect on particle generation, deposition rate,
	Engineering	uniformity, selectivity and incorporation into the film were
	Manager	examined. This work resulted in a 30% increase in deposition
		rate. Similarly, ppb-ppm levels of impurities were introduced
	Core	and accelerated lifetime tests were
	Technologist	quadrapole mass spectrometry gas composition in situ of
	U	Tungsten CVD and Al Etch process.
		• Responsible for gas, vacuum and chemical components
		evaluation, testing and supplier quality management. Managed
		an engineering group that tested and recommended gas, vacuum

	CVD Engineering Manager	 and chemical components for the CVD division, and developed process controls at suppliers. Supervised laboratory and trained individuals to develop specialized testing capabilities to characterize gas delivery and vacuum components. Also supported Etch, PVD and other divisions with common suppliers including vacuum pumps, vacuum transducers, flow controllers, valves and similar. Managed group of engineers and support personnel who developed gas panels and liquid source delivery systems for dielectric deposition. Delivered TEOS, TMP, TMB and many other organometallic precursors for SG, BPSG dielectric deposition. Developed organometallic CVD systems extensively. Designed multiple liquid source delivery systems for organometallic chemical precursors, i.e. bubblers, boilers, injectors. Managed CVD division design support group: CAD designers, drafters and CAD systems for division. Brought in first FEA program. Established and managed the customer engineering special group for the CVD division, which engineered all equipment modifications to meet customer specifications. These modifications included changes across the entire system, including process chambers, vacuum systems, gas delivery, power distribution, safety and robotics. Worked on the development and release of the landmark product, Precision 5000 CVD, one of which is now in the Smithsonian Institute. This was the first cluster tool for semiconductor manufacturing. Developed dielectric layers of silicon dioxide (glass or USG), boron phosphorous silicon glass (BPSG), phosphorous silicon glass (PSG), phosphorous silicon glass (PSG), nitride, oxy-nitride, and others. Responsible for flow and vacuum equipment suppliers for company including MFC, valves, mechanical vacuum pumps, cryo-pumps, dry pumps, and others. Supported multiple
Doctoral	Dissortatio	divisions on these matters.
From:	1996	Stanford University
To:	2002	Stanford, California Ph.D.

Completed a dissertation in the department of Materials Science & Engineering leading to the Ph.D. degree. Research includes:

• Plasma Deposition of Diamond-Like Carbon and Fluorinated Amorphous Carbon and the Resultant Properties and Structure

• Characterized stress, strain and hardness of films. Related the stress energy state to the diamond like nature of the thin films.

• Investigation of deposition mechanism fluorinated amorphous carbon (FLAC) and diamond-like carbon (DLC), low k dielectric materials.

• Modeled and conducted experiments on mechanism of ion energy, momentum and flux dependence for FLAC and DLC film synthesis in radio-frequency plasma discharges, including competing mechanisms of sub-plantation, ion-peening, sputtering, and etching.

• Constructed and instrumented a multi-purpose processing chamber for CVD, etch, and sputtering with measurement capability.

• Fabricated MIS capacitors to investigate the dielectric properties of fluorinated amorphous carbon (FLAC). Performed all wafer processing to construct MIS capacitors, including lithography, etch, CVD and PVD.

• Conducted thin film analysis including UV absorption spectroscopy, spectral ellipsometry, multi incident angle ellipsometry, Fourier transform infrared spectroscopy, profilometry, nano-indentation, and gravimetric measurements.

• Modeled dielectric properties and dispersion relationship of fluorinated amorphous carbon (FLAC), and compared spectral ellipsometric measurements to results of electrical CV tests and thickness measurements by profilometry using MIS structures.

Consulting History (Partial before 2010)

From To	Sept. 2017 present	UNICO Finite element analysis of new product concepts.
From To	July 2017 present	Elwood National Forge Professional Engineering review of capital equipment. Finite element analysis.
From To	April 2017 May 2017	Jon Richards Co. (for Disneyland) Professional Engineering review of electric vehicle used as float at Disneyland.
From To	2017 Ongoing	Licensed Mechanical Engineering Professional Engineering letters and calculations for submission to building and environmental health departments. Miscellaneous clients.

From To:	2016 Ongoing	Confidential Client Reverse engineering of OLED display technology.	
From To:	2016 2017	VWR Review of new semiconductor technologies for etching and particle reduction in semiconductor processing chambers.	
From To:	2016 2017	TDA Research Finite element analysis of effluent treatment system for power plant carbon reduction treatments.	
From To:	2016 Ongoing	Champion Telecom Engineering support, Finite element analysis, and design of "Cell Towers on Wheels" (COWs). Multiple projects. Analysis of trucks used to support emergency telecommunications.	
From To:	2016 Ongoing	CarbonTech Pursue UL listing for thin film carbon heaters. Help productize the technology. Review codes for domestic use.	
From To:	2015 2016	Phiston Engineering Review ability of equipment to destroy flash memory. Generate report to submit to NSA.	
From To:	2015 2015 Duties	United States Air Force Concluded Advanced semiconductor process equipment engineering for Air Force Laboratory.	
From	2013	United States Department of Justice, Antitrust Division	
To:	2014 Duties	Served as the industry expert for the DOJ in their investigation of the proposed merger between Applied Materials and Tokyo Electron.	
From	2015 Ongoing	VADA	
To:	Ungoing Duties	Fluid analysis of venting device.	
From To:	2014 Completed Duties	Chemithon	
		Finite element analysis (FEA) and computational fluid dynamics (CFD) analysis of thermal and stress analysis of large industrial	

sized heat exchangers. Redesign to meet structural and performance needs.

From To:	2013 2013	Barrick Cortes Mines		
101	Duties	Analysis of equipment using in mining operations.		
From	2013 2013	Life Technologies		
	Duties	Concept design for a portion of a medical device: centrifuge assembly for separation in PCR DNA application.		
From To:	2012 2012	Light failures		
10.	Duties	Reliability analysis of thermal issues causing light sealing failures for glass metal interface.		
From	2012 2012	Legion Industries		
10.	Duties	Review of electrical surge issues at Google campus.		
From	Dec. 2011 2012 Duties	CareFusion		
101		Chemical compatibility/reliability analysis of medical device.		
From To:	June 2011 2012 Duties	Watlow		
10.		Heater and chuck assembly design for use in semiconductor processing.		
From To:	June 2011 June 2012	Limited Brands		
	Duties	Design review of prototype consumer electronics products. Perform engineering analysis of weaknesses and risks in product design.		
From	April 2011	EFCI/Environmental Protection Agency		
10.	Duties	Subject matter expert for green house gas emissions from the electronics industry.		
From	June 2011 Current Duties	Intrimed		
10.		Consult for Exec. VP on thin film technology in medical devices.		
From	April 2010	Zoll Circulation		

To:	June 2010 Duties	Analysis of electrical contacts in a medical device, cardiac life support pump.	
From:	June 2008 Sept. 2008	Teardown and analysis of IC packaging.	
From To:	Oct 2008 Feb 2009	VModa	
Duties		Engineering analysis of headset/earbuds used for iPhone. Performed finite element analysis (FEA) of plug to determine why the plug/cable contacts were breaking. Reviewed designs of a number of competing earbuds, and other musical equipment plugs, and their respective designs for plug reliability improvements.	
From	Sep 2008	Malema Sensor	
10.	Duties	Safety Analysis of Fluid dispense system for semiconductor equipment.	
From	Dec 2007	Damage analysis for insurance valuation.	
10:	Jan 2008 Duties	Analysis of damage to equipment from a chemical leak.	
From:	Apr 2007 Oct 2008 Duties	Epicrew	
To:		Finite element analysis of temperature distribution in process chamber, and leading to safety issues and analysis of emergency conditions in epitaxial equipment. Multi-physics transient radiation, conduction and convection analysis.	
From:	Apr 2007	Unicor	
10.	Duties	Analysis by FEA and approval of automotive lifting devices as a licensed mechanical engineer.	
From:	2007	Altcatel	
10.	Duties:	Consulting on semiconductor foundry processes, low-k spin on dielectrics, that lead to IC failures.	
From:	2002		
To:	Present	Consulting with financial analysts on semiconductor industry through Gerson Lehrman Group.	
	Duties:	Provided on the spot analysis of new technologies, companies, and products within the semiconductor and related industry.	

From: To:	March 2004 2009 Duties:	AIU (Now Chartis Insurance.) Hsinchu, Taiwan Analysis of complete destruction of FAB due to facility design, equipment design, installation, process monitoring and control, etc. International Arbitration.	
From: To:	June 2004 Nov 2004 Duties:	Rosemont Process, Division of Emerson Electric, Inc. Minneapolis, MN. Market analysis of process monitoring and control needs.	
From: To:	Oct 2000 March	Brooks Instrument, Division of Emerson Electric, Inc. Hattfield, PA, and Minneapolis, MN.	
	Duties:	Market analysis of semiconductor equipment needs with respect to fluid handling components.	
From: To	Apr 2000 Oct 2000 Duties:	Lebar, Inc. Sunnyvale, CA System design and fluid delivery system design for plasma based photoresist strip (photoresist removal).	
From: To	Dec 1999 2000 Duties:	High Speed Industries, Inc. Lake Elsinore, CA Market analysis of semiconductor equipment needs with respect to fluid handling components.	
From:	May 1999 Duties:	Aeroquip (Division of Eaton Corp.) Ann Arbor, MI Reviewed new product entry (semiconductor fluid handling) prior to product engineering.	
From: To:	Sep 1999 Nov 1999 Duties:	Steag RTP Systems, Inc. San Jose, CA. Materials evaluation and testing for metallic reduction in thermal SiO ₂ films produced by rapid thermal processing (RTP) with steam.	
From: To:	Sep 1998 Aug 1999 Duties:	Cymer, Inc. San Diego, CA Project manager responsible for leading team through concept and feasibility studies for major product enhancement to Excimer laser used in deep ultraviolet lithography.	
From: To:	Jan 1997 Sep 1998	Millipore, Inc. Rancho Bernardo, CA	

Duties:	• Established a metrology group responsible for vacuum and
	flow measurements. The metrology is used in the manufacture and
	service of instruments for semiconductor process equipment.
	Established statistical process control for production metrology
	equipment. Established statistical process control on factory floor.

• Led development team for new mass flow control device.

Testimony in the Last Six Years

Client	IP Bridge (Ropes and Gray)		
Case	BROADCOM LIMITED, BROADCOM CORPORATION, AVAGO TECHNOLOGIES, LTD., AVAGO TECHNOLOGIES U.S., INC., and LS CORPORATION, Case No. 2:16-cv-134, Eastern District of Texas, and IPR2016-1376, 1377 and 1379.		
Project	Interconnect and back end of line patents.		
Dates	Spring 2015 – Spring 2017		
Status	Submitted expert reports and testified at deposition.		
Client	Elm 3DS Innovations (Mintz, Levin, Cohn, Ferris, Glovsky and Popeo PC)		
Case	Elm v. Samsung Electronics, Hynix and Micron Inter Partes Review (IPR) at the USPTO: IPR2016-00386, IPR2016-00387, IPR2016-00388, IPR2016-00389, IPR2016- 00390, IPR2016-00391, IPR2016-00392, IPR2016-00393, IPR2016-00394, IPR2016-00395, IPR2016-00687, IPR2016- 00691, IPR2016-00708, IPR2016-00770, and IPR2016-00786 Cooke		
Project	Patent infringement involving thinned and stacked wafers, low stress dielectric materials and other topics of IC memory.		
Dates Status	2016 - 2017 Submitted declarations in IPR and gave testimony at deposition.		
Client Case	Semcon, (Russ, August & Kabat) Semcon v. Micron Inc. CASE NO. 12-532-RGA UNITED STATES DISTRICT COURT FOR THE DISTRICT OF DELAWARE		
Project	Advanced process control and metrology in semiconductor processing patent case regard CMP.		
Dates Status	2013 Submitted expert reports and testified at deposition.		

Client Case	Caterpillar Inc., (Baker & Hostetler) Miller UK Limited v. Caterpillar Inc. CASE NO. 10-cv-3770 UNITED STATES DISTRICT COURT FOR THE NORTHERN DISTRICT OF ILLINOIS
	EASTERN DIVISION
Project	Trade secret case.
Dates	2013
Status	Submitted expert reports and testified at deposition and at trial. Completed.
Client	Carr & Farrell (LAM Research)
Case	LAM RESEARCH CORPORATION v. XYCARB CERAMICS
	CASE NO. 3:03-cv-1335 CRB
	UNITED STATES DISTRICT COURT
	NORTHERN DISTRICT OF CALIFORNIA
	SAN FRANCISCO DIVISION
Project	Review product for patent infringement.
Dates	2013
Status	Submitted reports and was deposed.Settled
Client	Schwegman, Lundberg & Woessner, P.A. (Amkor)
Case	Tessera v. Amkor. Petition for <i>inter partes</i> review of U.S. patent at USPTO
Project	Semiconductor manufacturing technology.
Dates	2013 – present
Status	Submitted declarations in IPR and gave testimony at deposition.

Patents

Patent Number	Date Issued	Title
7,118,090	Jan 20, 2007	Control Valves
6,679,476	Jan. 20, 2004	Control Valves
6,204,174	Mar. 20, 2001	Method and Apparatus Rate Deposition of
		Tungsten.
9,224,626	Dec. 29, 2015	Composite Substrate for Layered Heaters

Education

2003	Stanford University	Ph.D., Materials Science and Engineering
1995	Stanford University	M.S., Materials Science and Engineering
1987	University of California, Berkeley	M.S., Mechanical Engineering
1985	University of California, Berkeley	B.S., Mechanical Engineering

Publications and Conference Presentations (selected).

A.D. Glew, M.A. Cappelli, "Characterization and dielectric properties of fluorinated amorphous carbon measured by capacitance-voltage versus spectral ellipsometry", *Materials Research Society Symposium Proceedings*, **593**, Boston, MA, 1999, pp. 341-346.

A.D. Glew, M.A. Cappelli, "In situ plasma analysis, fluorine incorporation, thermostability, stress, and hardness comparison of fluorinated amorphous carbon and hydrogenated amorphous carbon thin films deposited on Si by plasma enhanced chemical vapor deposition", *Material Research Society Symposium Proc.*, **565**, San Francisco, CA 1999, pp 285-290.

A.D. Glew, R. Saha, M.A. Cappelli and J.S. Kim, "Ion Energy and Flux Dependence of Diamond Like Carbon Film Synthesis in Radio-Frequency Discharges", *International Conference on Metal Coatings and Thin Films*, Surface and Coatings Technology 114 (1999) 224-229.

A. Glew, R. Saha, M. Cappelli and J. Kim, "Ion Energy and Flux Dependence of Diamond Like Carbon Film Synthesis in Radio-Frequency Discharges", *International Conference on Metal Coatings and Thin Films*, San Diego, CA, April 1998

A. Glew, J, Ammenheuser, M. Crockett, A. Johnson, W. Dax, R. Binder, J. Riddle, "SEMASPEC 97043272A Accelerated Life Tests of Gas System Performance and Reliability," *http://www.sematech.org/public/docubase/abstract/3272atr.htm*.

A. Glew, J. Ammenheuser, J. Riddle, A. Johnson, "SEMASPEC 96083175A-XFR Determining the Effects of Impurities on Semiconductor Thin Film Processing," *http://www.sematech.org/public/docubase/abstract/3175axfr.htm.*

A Glew, "Selecting Gas Purity and Materials of Construction in High Purity Gas Systems," *Semicon West Symposium on Corrosion*, July 1997

Glew, J. Kim, K. Lee, M. Cappelli, "On the Characteristics of Diamond Like Carbon",A. *International Conference on Metal Coatings and Thin Films*, San Diego, CA, April 1997

A. Glew, D. Porter, "Gas System Reliability Testing in Chlorine", *Semiconductor Fabtech*, May 1996.

Professional Associations

American Society of Mechanical Engineers (ASME) International Microelectronics and Packaging Society Materials Research Society (MRS) IEEE SEMI

Professional License

Licensed Mechanical Engineer, State of California, M26690

Laboratory analysis

On site: Microscopy, Vis and Near IR spectroscopy, thermal measurements, electricalmechanical measurements.

Other Laboratory analysis may be provided through supervised third party laboratories: SEM, TEM, ESCA, AES, SIMS, FTIR, AFM

Technical Software Packages and Programming Languages (Selected):

Autodesk Simulation MechanicalTM (AlgorTM and NastranTM) 2018 Autodesk Simulation CFD (CF DesignTM) 2018 Autodesk InventorTM, Computer Aided Design 2018 Autodesk AutoCADTM, Computer Aided Design 2018 PTC CreoTM 4.0 MathematicaTM 11: mathematical analysis SolidworksTM 2018

Civic Duties

Chairman & Commissioner of the Design Review Commission, Los Altos, CA.

Volunteer and Service Activities

Los Altos Rotary Club Board of Director: Responsible for Operations Veterans Committee and others

University of California Alumni Association (UC Berkeley) Alumni Awards Committee 2015 Alumni Awards Committee 2014 Alumni Awards Committee 2013

NorCal Golden Retriever Club

For more information please contact:

Glew Engineering Consulting Inc. 240 Pamela Drive Mountain View, CA 94040

Tel:800-877-5892 (Toll Free USA)Tel:650 4641 3109 (Main number)Tel:650 403-2063 (Office direct)Fax:650-292-2210Email:adglew@glewengineering.comWeb:www.glewengineering.com